

2222 Wellington Court Lisle, IL 60532 USA

Product Compliance Declaration

Please see <u>www.molex.com</u> for the most up-to-date information.

Contact Information				
Name	Molex Product Compliance	E-Mail	Product.Compliance@molex.com	
Part Inform	ation			
Part Number	0330013023	Part Weight	0.434996G	
Part Name	MX150 RCPT 0.3 GOLD 22AWG D WIND UNSLD			

Product Composition

Name	Туре	CAS Number	Proportion (% Total)	Mass (Grams)
MX150 RCPT 0.3 GOLD 22AWG D WIND UNSLD	Assembly		100	0.434996
MX150 RCPT 0.3 GOLD 22AWG B WIND UNSLD	Component		100	0.434996
HSM Copper Unplated	Material		99.3112	0.432
Copper	Substance	7440-50-8	97.3746	0.423576
Nickel	Substance	7440-02-0	0.9931	0.00432
Tin	Substance	7440-31-5	0.8938	0.003888
Phosphorus	Substance	7723-14-0	0.0497	0.000216
Gold Plating	Material		0.0365	0.000159
Cobalt	Substance	7440-48-4	9E-05	4E-07
Nickel	Substance	7440-02-0	9E-05	4E-07
Gold	Substance	7440-57-5	0.0363	0.000158
Tin Plating	Material		0.1236	0.000538
Tin	Substance	7440-31-5	0.1236	0.000538

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Name	Туре	CAS Number	Proportion (% Total)	Mass (Grams)
Nickel Plating	Material		0.5287	0.0023
Nickel	Substance	7440-02-0	0.5287	0.0023
Further Additives, not to declare	Substance	system	5E-05	2E-07

HFLH Declaration Information

Regulatory Revision IEC 61249-2-21

Contained Substances Exceeding Threshold

Not reviewed

ROHS Declaration Information

Regulatory Revision EU 2015/863

Compliance Status Compliant

Contained Substances Exceeding Threshold

None

Exemptions

None

REACH-SVHC Declaration Information

Regulatory Revision D(2020)9139-DC (19 Jan 2021)

Contained Substances Exceeding Threshold

None

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GADSL Declaration Information

Regulatory Revision GADSL imported from IMDS

Contained Substances Exceeding Threshold

Substance Group	Substance Location	Threshold (PPM)	Concentration (PPM)	Intentionally Added
lead		*Note	500	Yes
nickel powder [particle diameter < 1 mm]	e-plate Au (Hardgold) (electrodeposited Hardgold	*Note	2,500	Yes
nickel powder [particle diameter < 1 mm]	High Copper Alloy (NB109)	*Note	10,000	Yes
nickel powder [particle diameter < 1 mm]	Ep-Ni	*Note	997,500	Yes
silver	High Copper Alloy (NB109)	*Note	500	Yes
Cobalt	e-plate Au (Hardgold) (electrodeposited Hardgold	*Note	2,500	Yes
copper	High Copper Alloy (NB109)	*Note	977,000	Yes

*Note: For GADSL substance declarable/prohibited threshold values, please reference http://www.gadsl.org/

Exemptions

Part Name	Exemption
	44 Concentration within acceptable GADSL limits
e-plate Au (Hardgold) (electrodeposited Hardgold Coatings)	34 Not applicable
High Copper Alloy (NB109)	34 Not applicable
Ep-Ni	33 Other application (Surface not routinely touched or nickel release rate < 0.5µg/ cm2/week)

Process Information

Component Plating / Surface Finish	N/A
Termination Base Alloy	N/A
Solder Alloy	N/A
Process Capability	N/A
Maximum Exposure Time (seconds)	N/A
Maximum Process Temperature (C)	N/A
Maximum Cycles at Reflow Temperature	N/A
J-STD-020 Moisture Sensitivity Level	N/A

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Mar 24, 2021

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